

Advanced LLE Aware Design Methodology

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Methodology
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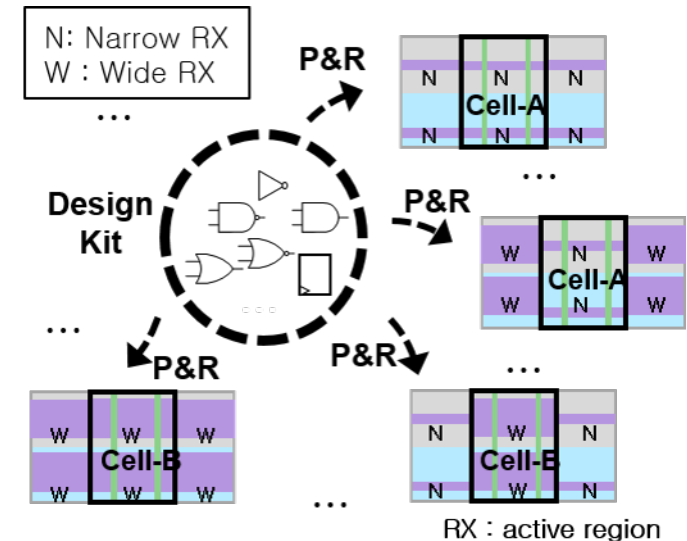
Introduction



- In advanced process node, the impact of LLE so large that it cannot be ignored, and has become a level that must be considered at the design stage
- In this presentation, we introduce LLE aware design methodology from characterization to timing signoff for accurate timing and power analysis

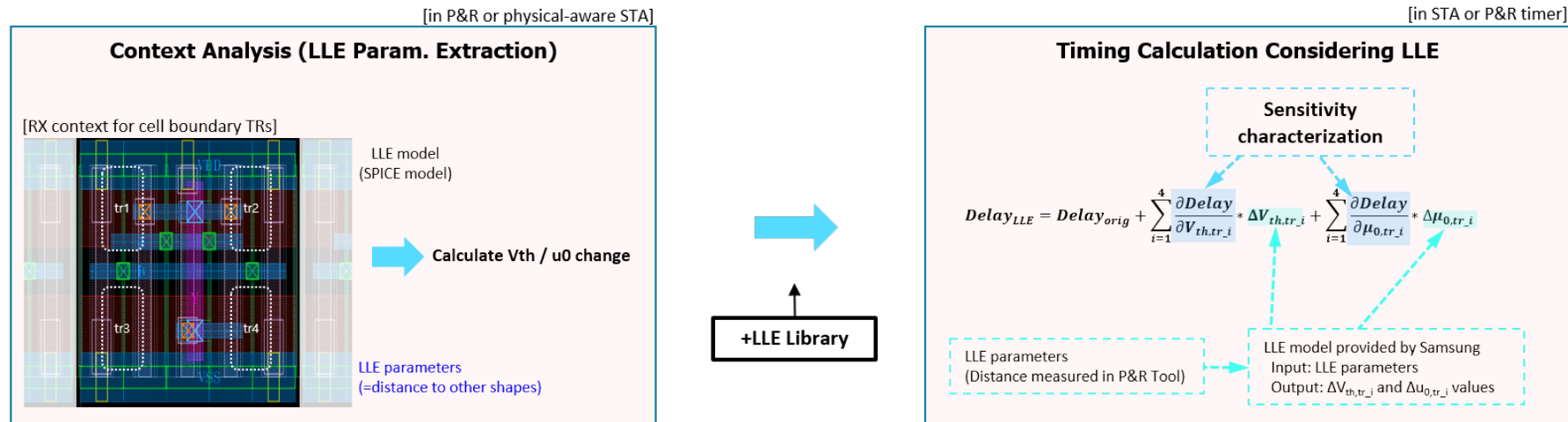
Motivation

- LLE (Local Layout Effect)
 - Electronic characteristics change according to the neighbor pattern
- Motivation
 - Conventional design method for DK characterization uses min/max overlay for timing min/max bound
 - There are various Nano-Sheet (NS) options
 - Lots of design contexts from NS combinations
 - Fixed overlay makes mismatch between overlay and actual context
 - Need to fill the gap between actual context and fixed overlay
- LLE aware design methodology is needed



Proposal Idea

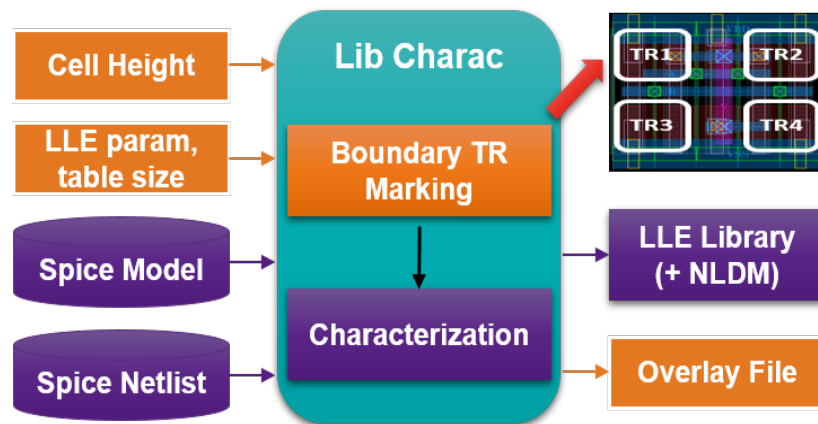
- Basic Concept
 - LLE impact is presented as V_{th} and u_0 change, and then translated into delay change
 - LLE related context can be extracted from physical DB
 - LLE impact on delay can be calculated with design context (V_{th} , u_0 change)
- LLE Sensitivity Library
 - Timing impact per cell boundary transistor's parameter shift is characterized for each timing arc



Sensitivity Library Characterization

- Sensitivity Characterization

- LLE impact is modelled for
 - Boundary transistors
 - timing (delay/slew), leakage power
 - Perturbation parameters (Vth, u0)
- Needed information
 - Cell height for boundary transistor recognition
 - Perturbation values for LLE parameters
 - Index points (table size)

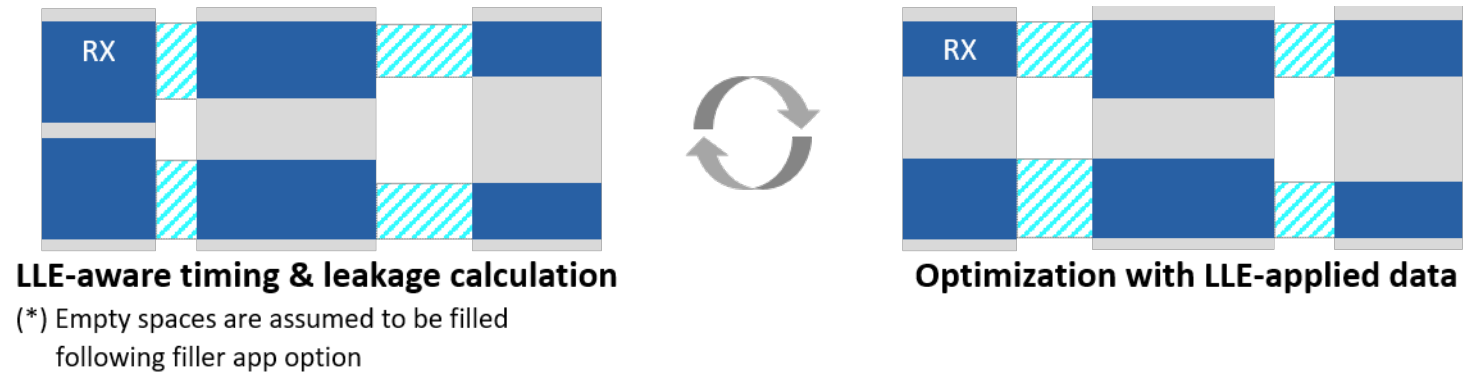


Sample Liberty Format

```
cell(test_cell) {
leakage_power() {
  related_pg_pin : "VDD" ;
  when : "!A&!B&!CI&!CO&!S" ;
  value : "2.91394e-05" ; ## origin leakage value
  ...
lle_delta_leakage_power(lle_lkg_delta_2) {
  related_params : "vth" ; ## param definition > Vth or u0
  related_devices : "tr1" ; ## boundary tr definition > tr1, tr2, tr3, tr4 ....
  index_1("-0.015, 0.015") ; ## perturbation value of parameter
  values("2.87158e-09, -2.56085e-09") ; ## sensitivity (delta value)
}
}
...
}
...
pin(Y)
timing() {
  ...
cell_fall(8x8) {
  index_1("...") ;
  index_2("...") ;
  values("...") ; ## origin timing table
}
...
lle_delta_cell_fall(lle_1x3x3) {
  related_params : "vth" ; ## param definition > Vth or u0
  related_devces : "tr1" ; ## boundary tr definition > tr1, tr2, tr3, tr4 ....
  index_1("0.015") ; ## perturbation value of parameter
  index_2("0.0011535, 0.102186, 0.809411") ; ## index from origin index
  index_3("8.5511e-05, 0.00230265, 0.0355597") ;
  values("-1.51201e-06, -2.65675e-07, 6.45165e-09",\
  "-1.87921e-07, -3.77126e-07, -1.41947e-07",\
  "1.25844e-06, -1.54662e-05, -1.19289e-05") ; ## sensitivity (delta value)
}
}
...
}
```

LLE Aware Place and Route

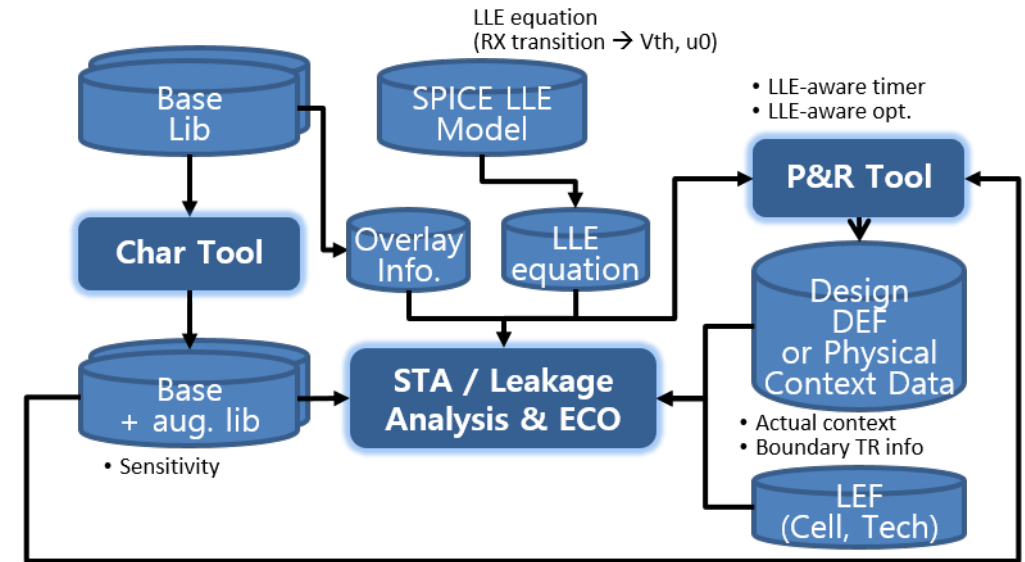
- PNR engine considers LLE effect in timing and leakage power calculation
 - Optimize and legalize with resizing cells by using LLE sensitivity for accurate data



LLE Aware Timing Analysis

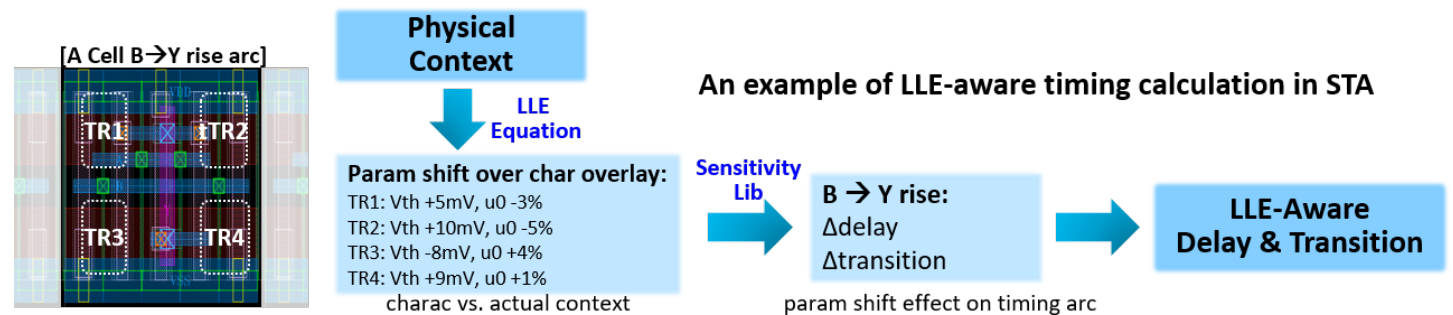
- Overall Flow and Required Collaterals

- LLE sensitivity libraries
 - Timing arc sensitivity per victim transistor impact
- LLE model and overlay information
 - DLL compiled with LLE impact equations
 - Characterization Overlay (as a shift baseline)
- DEF and LEF (Design context)
 - For context information and boundary TR mapping



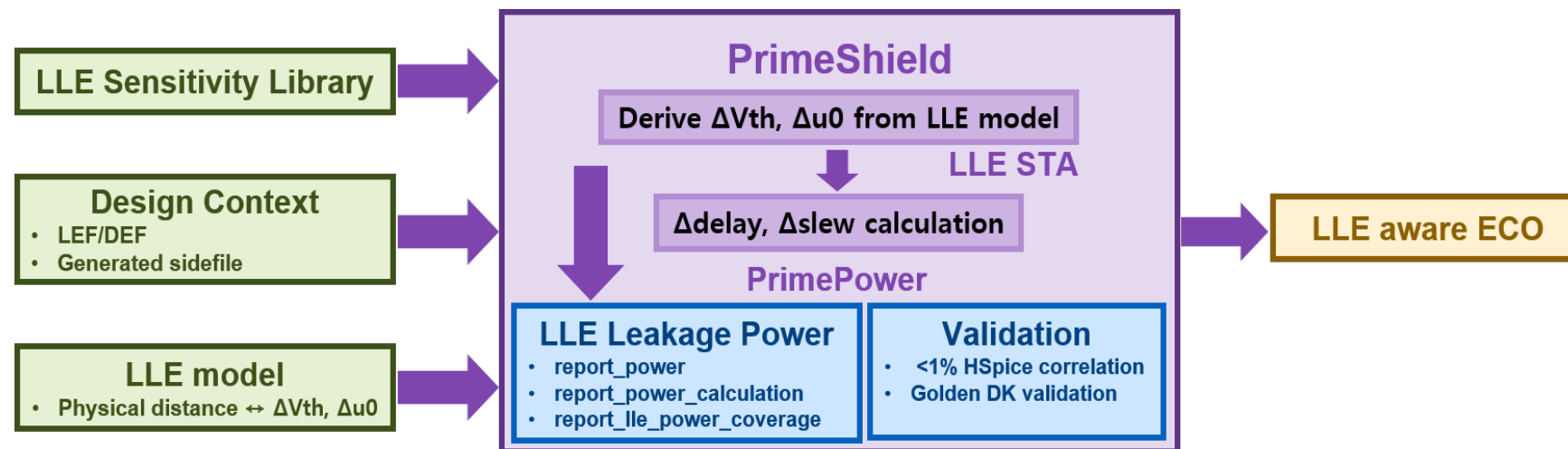
- Delay Calculation in STA

- Recognize neighbor cell (transition or not)
- Calculate parameter shift value (Vth, u0)
- Apply parameter shift value
- Delay calculation



LLE Aware Power Analysis

- Overall Flow and Required Collaterals
 - Similar design flow and input collaterals as LLE STA
- LLE Leakage power calculation
 - Leakage varies linearly with mobility (μ_0) and quadratically with threshold voltage (V_{th}) shift
 - For FFPG (SSPG) corner, leakage generally *decreases* (*increases*) when LLE is ON
 - PrimePower leakage power accuracy within 1% of HSpice simulation and Golden DK results
 - New “physDB lite mode” flow for full chip LLE signoff support

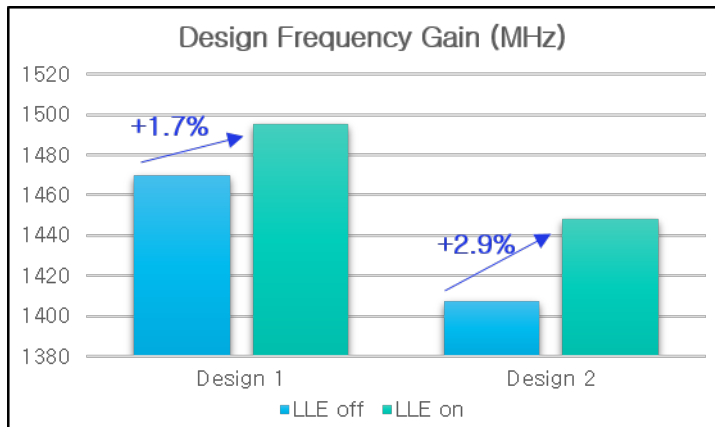


Validation and Design Gain

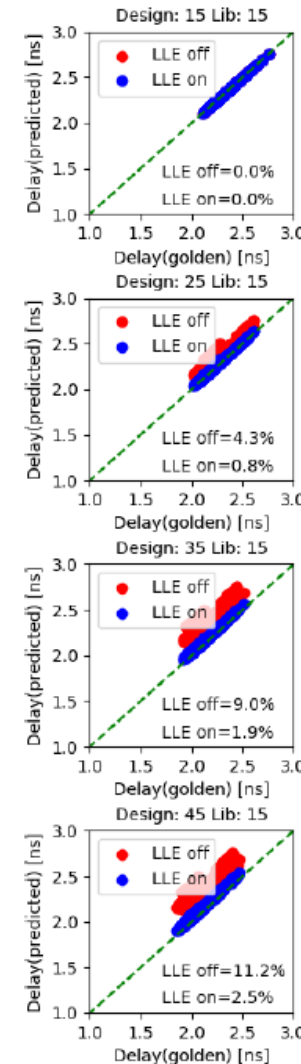
- Validation : STA-SPICE Correlation
 - Design with various NS width cells
 - Between all instances, have enough space for filler cell
 - Same NS filler cells are inserted in this space
 - Check STA-SPICE correlation by all NS cases
 - Shows better correlation with LLE aware Flow

- Signoff Gain

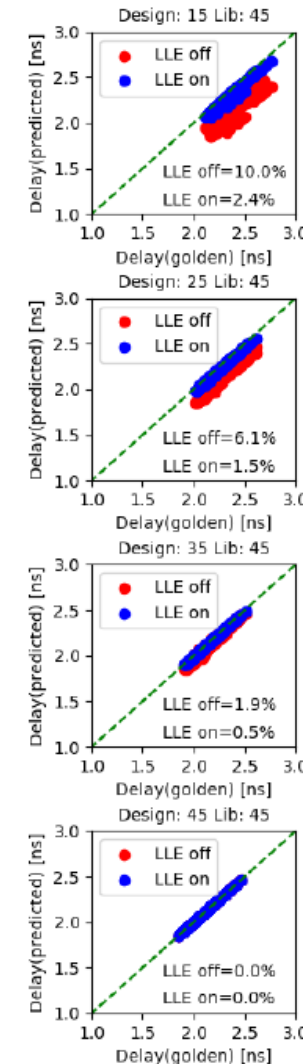
- Shows around 2% design frequency gain



SSPG corner



FFPG corner



Conclusion

- In advanced node, LLE impact in design flow is no longer negligible
 - Especially with conventional overlay condition
- LLE impact can be reflected in design flow with the methodology presented
- LLE impact of each boundary transistor should be modelled in library by SPICE parameters
- In PNR stage, the tool optimizes design by resizing consuming LLE sensitivity
- In STA stage, the tool determines updated timing of each cell by considering it's neighbors
- In power analysis, the tool calculates accurate leakage power with LLE term
- Considering LLE impact yielded 2-3% frequency gain on designs

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THANK YOU

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